

EAST - [capacitor to via.wsp.1]

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- L4: (6786) ["257/684,690,707,737,778,668,666"].CCLS.
- L5: (0) ["4 and "tape carrier package"'].PN.
- L6: (95) 4 and "tape carrier package"
- L8: (0) 7 and leadframe
- L9: (408) 4 and leadframe
- L10: (0) 9 and "tape carrier package"
- L7: (34) 6 and "Tape automated bonding"
- L11: (308) 4 and (col or loc)
- L12: (2) 11 and "tape carrier package"

Failed

(0) (f (col or chip-on-lead)) and semiconductor) and (f "polym

Search filters:

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11 and "tape carrier package"

Search results table:

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|---|--------------------------|--------------------------|----------------------|-----|-----------------|--|------------|------------------------------------|-------------------|-------------------------------|
| 1 | <input type="checkbox"/> | <input type="checkbox"/> | US 20010002066 A1 | | 42 | Semiconductor device, lead-patterning substrate, and electronics device. | | | | Mita, Mamoru Murakami, Gen |
| 2 | <input type="checkbox"/> | <input type="checkbox"/> | US 5894107 A | 199 | 11 904 13 | Chip-size package (CSP) using a multi-layer laminated lead frame | 174/52.2 | 174/52.4 ; 257/676 ; 257/693 | | Lee, Kyu Jin et al. |

LOC

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| EAST [capacitor to via.wsp.1] | | | | | | | | | | |
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| File View Edit Tools Window Help | | | | | | | | | | |
| <input type="checkbox"/> Pending <input checked="" type="checkbox"/> Active 1.1: (241) "tape carrier package" and "tape automated bonding" | | | | | | | | | | |
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| | U | I | Document ID | Iss | Page | Title | Current OF | Current XRef | Retrieval Classif | In |
| 6 | <input checked="" type="checkbox"/> | <input type="checkbox"/> | US 6125042 A | 200 009 26 | 10 | Ball grid array semiconductor package having improved EMI characteristics | 361/760 | 257/737 : 257/738 : 257/779 | | Verdi, Fred W. , et al. |
| 7 | <input checked="" type="checkbox"/> | <input type="checkbox"/> | US 6114754 A | 200 009 05 | 19 | Tape-automated bonding film | 257/668 | 257/673 : 257/778 | | Kata, Keiichiro |
| 8 | <input checked="" type="checkbox"/> | <input type="checkbox"/> | US 5895969 A | 199 904 20 | 16 | Thin type semiconductor device, module structure using the device and | 257/696 | 257/676 | | Masuda, Masa , et al. |
| 9 | <input checked="" type="checkbox"/> | <input type="checkbox"/> | US 5894107 A | 199 904 13 | 11 | Chip-size package (CSP) using a multi-layer laminated lead frame | 174/52.2 | 174/52.4 : 257/676 : 257/693 | | Lee, Kyu Jin , et al. |
| 10 | <input checked="" type="checkbox"/> | <input type="checkbox"/> | US 5821614 A | 199 810 13 | 30 | Card type semiconductor device | 257/679 | 235/492 : 257/712 : 257/713 | | Hashimoto, No , et al. |
| 11 | <input checked="" type="checkbox"/> | <input type="checkbox"/> | US 5818105 A | 199 810 06 | 16 | Semiconductor device with plastic material covering a semiconductor chip | 257/696 | 257/695 : 257/701 : 257/703 | | Kouda, Tsunen |
| 12 | <input checked="" type="checkbox"/> | <input type="checkbox"/> | US 5723903 A | 199 803 03 | 14 | Thin type semiconductor device, module structure using the device and | 257/696 | 257/676 : 257/686 : 257/787 | | Masuda, Masa , et al. |
| 13 | <input checked="" type="checkbox"/> | <input type="checkbox"/> | US 5586270 A | 199 612 17 | 21 | Method and apparatus for upgrading a central processing unit and | 710/301 | 710/13 : 711/130 | | Rotier, Michael , et al. |
| 14 | <input checked="" type="checkbox"/> | <input type="checkbox"/> | US 5446313 A | 199 508 29 | 13 | Thin type semiconductor device and module structure using the device | 257/666 | 257/686 : 257/702 : 257/787 | | Masuda, Masa , et al. |
| 15 | <input checked="" type="checkbox"/> | <input type="checkbox"/> | US 5410182 A | 199 504 25 | 9 | High density semiconductor device having inclined chip mounting | 257/692 | 257/775 : 257/776 | | Kurafuchi, Kazi , et al. |
| 16 | <input checked="" type="checkbox"/> | <input type="checkbox"/> | US 5349236 A | 199 409 20 | 17 | Reusable fixture for carrier tape | 257/701 | 206/713 : 257/668 : 257/727 | | Oshino, Fumio , et al. |

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|---|---|------------------|
| - | 241 | "tape carrier package" and "tape automated bonding" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/01/25 16:45 |
| - | 184 | ("tape carrier package" and "tape automated bonding") and semiconductor | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/01/25 16:46 |
| - | 16 | ((("tape carrier package" and "tape automated bonding") and semiconductor) and (thin near3 package) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/01/25 16:55 |
| - | 6786 | ("257/684,690,707,737,778,668,666").CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/01/25 16:56 |
| - | 0 | ("4 and "tape carrier package").PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/01/25 16:57 |
| - | 95 | ((("257/684,690,707,737,778,668,666").CCLS.) and "tape carrier package" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/01/25 16:57 |
| - | 0 | (((("257/684,690,707,737,778,668,666").CCLS.) and "tape carrier package") and "Tape automated bonding") and leadframe | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/01/25 16:58 |
| - | 408 | ((("257/684,690,707,737,778,668,666").CCLS.) and leadframe | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/01/25 16:58 |
| - | 0 | (((("257/684,690,707,737,778,668,666").CCLS.) and leadframe) and "tape carrier package" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/01/25 16:58 |
| - | 34 | (((("257/684,690,707,737,778,668,666").CCLS.) and "tape carrier package") and "Tape automated bonding" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/01/25 17:08 |
| - | 308 | ((("257/684,690,707,737,778,668,666").CCLS.) and (col or loc) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/01/25 17:09 |
| - | 2 | (((("257/684,690,707,737,778,668,666").CCLS.) and (col or loc)) and "tape carrier package" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/01/25 17:11 |

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|---|----|---|---|------------------|
| - | 33 | ((("257/684,690,707,737,778,668,666").CCLS.) and ("chip\$on\$lead" or chip-on-lead)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/01/25 17:12 |
| - | 0 | ((("257/684,690,707,737,778,668,666").CCLS.) and ("chip\$on\$lead" or chip-on-lead)) and "tape carrier package" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/01/25 17:13 |
| - | 17 | ((("257/684,690,707,737,778,668,666").CCLS.) and ("chip\$on\$lead" or chip-on-lead)) and "thin package" | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/01/25 17:13 |